IN THE CLAIMS:

Please amend claims 1-3, 9, 13 and 14 as follows:

1. (Currently amended) A method of manufacturing a semiconductor device comprising the step of:

forming a semiconductor film over a substrate;

forming an insulating film over the semiconductor film;

ion-doping an impurity element into a channel region of the semiconductor film through the insulating film,

wherein said impurity element imparts n-type conductivity or p-type conductivity to said semiconductor film,

wherein a concentration of said impurity element is in the range from 1×10^{15} to 5×10^{17} atoms/cm^3 in said semiconductor film after the step, and

wherein a concentration of carbon is at 3×10^{17} atoms/cm^3 or less in said semiconductor film after the step.

2. (Currently amended) A method of manufacturing a semiconductor device comprising the step of:

forming a semiconductor film over a substrate;

forming an insulating film over the semiconductor film;

ion-doping an impurity element into a channel region of the semiconductor film through the insulating film,

wherein said impurity element imparts n-type conductivity or p-type conductivity to said semiconductor film,

wherein a concentration of said impurity element is in the range from 1×10^{15} to 5×10^{17} atoms/cm^3 in said semiconductor film after the step, and

wherein a concentration of nitrogen is at 1×10^{17} atoms/cm^3 or less in said semiconductor film after the step.

3. (Currently amended) A method of manufacturing a semiconductor device comprising the step of:

forming a semiconductor film over a substrate;

forming an insulating film over the semiconductor film;

ion-doping an impurity element into a channel region of the semiconductor film through the insulating film,

wherein said impurity element imparts n-type conductivity or p-type conductivity to said semiconductor film,

wherein a concentration of said impurity element is in the range from 1×10^{15} to 5×10^{17} atoms/cm^3 in said semiconductor film after the step, and

wherein a concentration of oxygen is at 3×10^{17} atoms/cm^3 or less in said semiconductor film after the step.

4. (Original) A method of manufacturing a semiconductor device according to any one of claims 1 to 3, wherein no mass separation is performed in the ion-doping step.

5. (Original) A method of manufacturing a semiconductor device according to any one of claims 1 to 3, wherein said ion-doping is performed through an insulating film after providing said insulating film on said semiconductor film.

6. (Original) A method of manufacturing a semiconductor device according to any one of claims 1 to 3, wherein said semiconductor film is used as at least a channel forming region of a TFT.

7. (Original) A method of manufacturing a semiconductor device according to any one of claims 1 to 3, wherein said impurity element imparting p-type conductivity comprises a gas containing diborane, BF_2, or boron.

8. (Original) A method of manufacturing a semiconductor device according to any one of claims 1 to 3, wherein said impurity element imparting n-type conductivity comprises either one of a gas containing P or As, and phosphine.

9. (Currently Amended) A method for ~~for~~ fabricating a semiconductor device ~~fabricating a semiconductor device~~ according to any one of claims 1 to 3, wherein the impurity element imparting p-type conductivity is doped into the semiconductor film by employing a source material gas that contains diborane diluted with hydrogen to the concentration in the range from 0.5% to 5%.

10. (Original) A method of manufacturing a semiconductor device according to any one of claims 1 to 3, wherein the impurity element imparting p-type conductivity is doped

into the semiconductor film by employing a source material gas that contains diborane diluted with hydrogen to the concentration in the range from 0.5% to 1%.

11. (Original) A method of manufacturing a semiconductor device according to any one of claims 1 to 3, wherein the semiconductor device is one selected from the group consisting of a personal computer, a video camera, a portable information terminal, a digital camera, a digital video disk player, an electronic amusement apparatus, and a projector.

12. (Original) A method according to any one of claims 1 to 3, wherein the concentration of hydrogen to be ion-doped simultaneously with said impurity element in said semiconductor film is set to be at 1×10^{19} atoms/cm^3or less.

13. (Currently amended) A method of manufacturing a semiconductor device comprising the step of:

forming a semiconductor film over a substrate;

forming an insulating film over the semiconductor film;

ion-doping an impurity element into a channel region of the semiconductor film through the insulating film,

wherein said impurity element imparts n-type conductivity or p-type conductivity to said semiconductor film,

wherein a concentration of said impurity element is in the range from 1×10^{15} to 5×10^{17} atoms/cm^3 in said semiconductor film after the step, and

wherein a concentration of hydrogen is at 1×10^{19} atoms/cm^3 or less in said semiconductor film after the step.

14. (Currently amended) A method of manufacturing a semiconductor device comprising the step of:

forming a semiconductor film over a substrate;

forming an insulating film over the semiconductor film;

ion-doping an impurity element into a channel region of the semiconductor film through the insulating film,

wherein said impurity element imparts n-type conductivity or p-type conductivity to said semiconductor film,

wherein a concentration of said impurity element is in the range from 1×10^{15} to 5×10^{17} atoms/cm^3 in said semiconductor film after the step, and

wherein said impurity element is doped into said semiconductor film by using a source material gas containing said impurity element diluted with hydrogen to the concentration in the range from 0.5% to 5%.